

Features

- Green Device Available
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Advanced high cell density Trench technology

Description

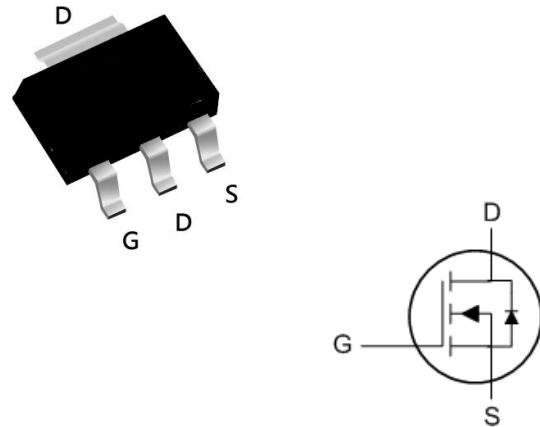
The JHL3002 is the high cell density trenched N-ch MOSFETs, which provides excellent R_{DS(on)} and efficiency for most of the small power switching and load switch applications.

The JHL3002 meet the RoHS and Green Product requirement with full function reliability approved.

Product Summary

| BVDSS | R _{DS(on)} | I _D |
|-------|---------------------|----------------|
| 30V | 28mΩ | 5.8A |

SOT-223 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|--------------------------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | 30 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _A =25°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 5.8 | A |
| I _D @T _A =70°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 4.7 | A |
| I _{DM} | Pulsed Drain Current ² | 30 | A |
| P _D @T _A =25°C | Total Power Dissipation ³ | 1.5 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-ambient ¹ | --- | 85 | °C/W |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | --- | 48 | °C/W |

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|------------------------------|--|---|------|-------|-----------|----------------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | 30 | --- | --- | V |
| $\Delta BV_{DSS}/\Delta T_J$ | BVDSS Temperature Coefficient | Reference to 25°C , $I_D=1\text{mA}$ | --- | 0.025 | --- | $V/^\circ\text{C}$ |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=10V, I_D=5A$ | --- | 24 | 28 | m Ω |
| | | $V_{GS}=4.5V, I_D=4A$ | --- | 34 | 40 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}, I_D=250\mu A$ | 1.2 | 1.5 | 2.5 | V |
| $\Delta V_{GS(th)}$ | $V_{GS(th)}$ Temperature Coefficient | | --- | -4.8 | --- | $\text{mV}/^\circ\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=24V, V_{GS}=0V, T_J=25^\circ\text{C}$ | --- | --- | 1 | μA |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=24V, V_{GS}=0V, T_J=25^\circ\text{C}$ | --- | --- | 5 | μA |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V, V_{DS}=0V$ | --- | --- | ± 100 | nA |
| gfs | Forward Transconductance | $V_{DS}=5V, I_D=5A$ | --- | 7 | --- | S |
| R_g | Gate Resistance | $V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$ | --- | 2.5 | 5 | Ω |
| Q_g | Total Gate Charge (4.5V) | $V_{DS}=15V, V_{GS}=4.5V, I_D=5A$ | --- | 6 | 8.4 | nC |
| Q_{gs} | Gate-Source Charge | | --- | 2.5 | 3.5 | |
| Q_{gd} | Gate-Drain Charge | | --- | 2.1 | 2.9 | |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega$ $I_D=5A$ | --- | 2.4 | 4.8 | ns |
| T_r | Rise Time | | --- | 7.8 | 14 | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 22 | 44 | |
| T_f | Fall Time | | --- | 4 | 8 | |
| C_{iss} | Input Capacitance | $V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$ | --- | 572 | 800 | pF |
| C_{oss} | Output Capacitance | | --- | 81 | 112 | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 65 | 91 | |
| Diode Characteristics | | | | | | |
| I_S | Continuous Source Current ^{1,4} | $V_G=V_D=0V$, Force Current | --- | --- | 5.8 | A |
| I_{SM} | Pulsed Source Current ^{2,4} | | --- | --- | 30 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$ | --- | --- | 1.2 | V |
| t_{rr} | Reverse Recovery Time | $I_F=5A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$ | --- | 19 | --- | nS |
| Q_{rr} | Reverse Recovery Charge | | --- | 1.04 | --- | nC |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_S , in real applications , should be limited by total power dissipation.

Typical Characteristics

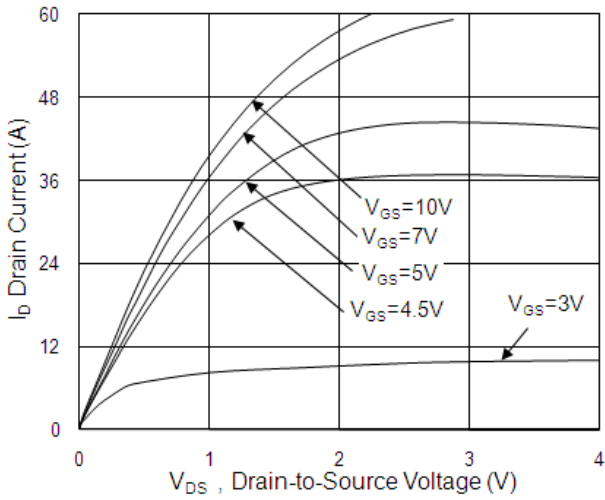


Fig.1 Typical Output Characteristics

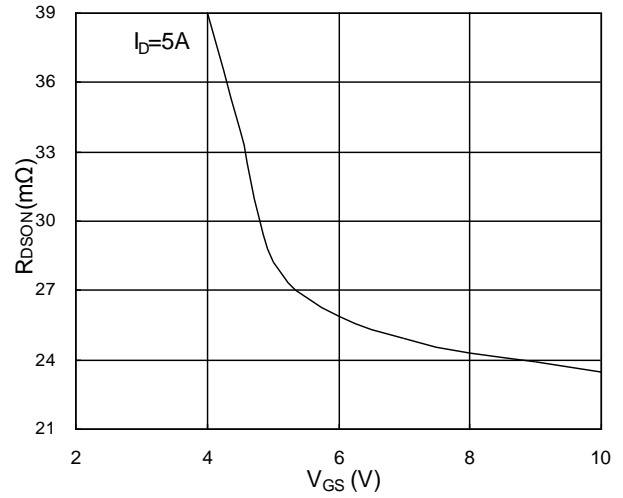


Fig.2 On-Resistance vs. Gate-Source

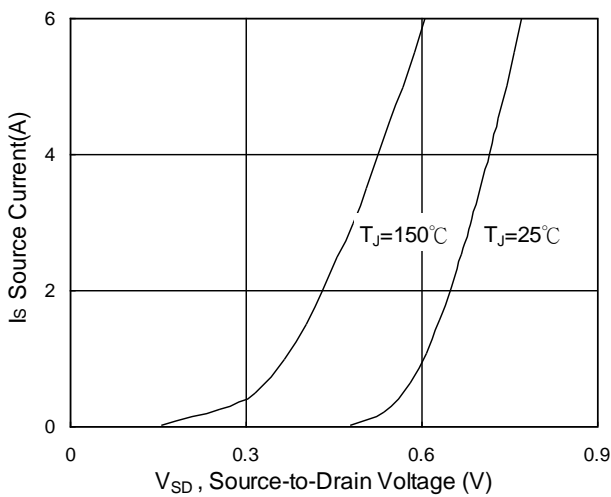


Fig.3 Forward Characteristics of Reverse

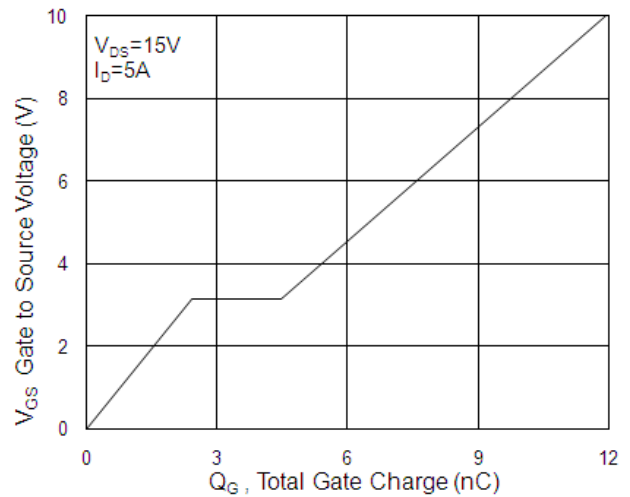


Fig.4 Gate-Charge Characteristics

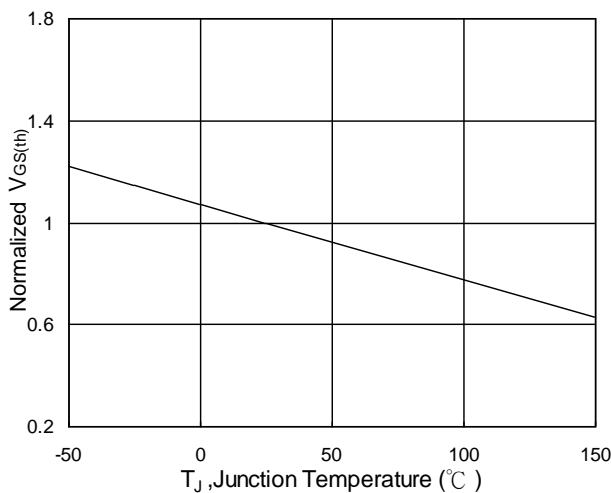


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

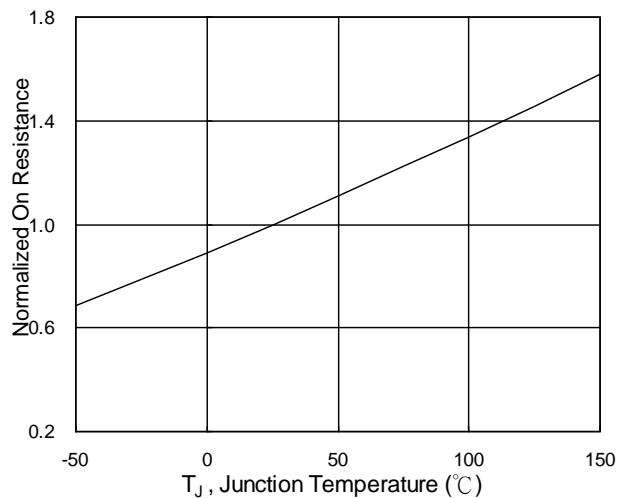


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

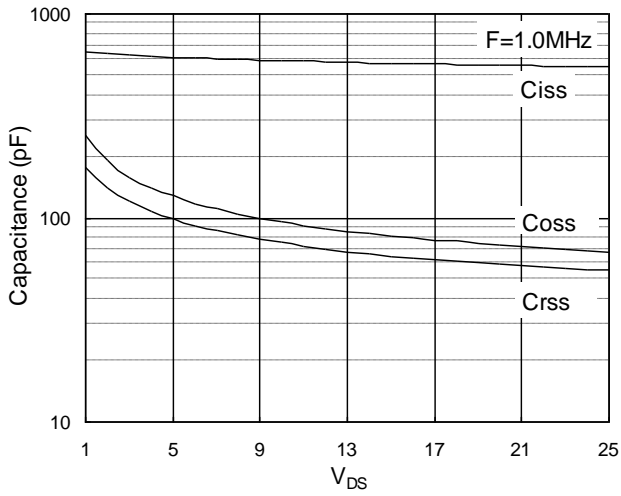


Fig.7 Capacitance

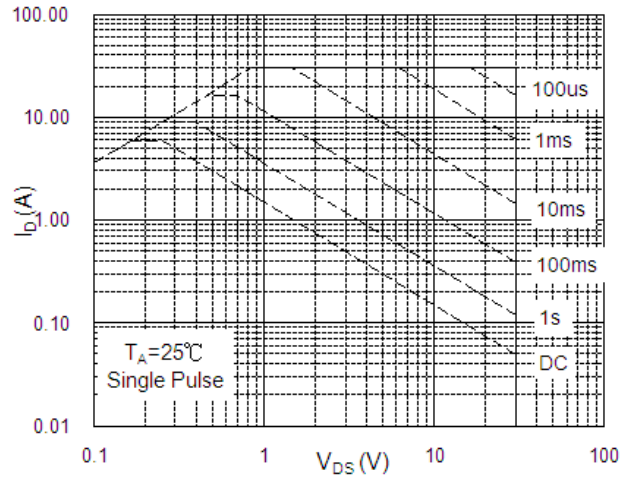


Fig.8 Safe Operating Area

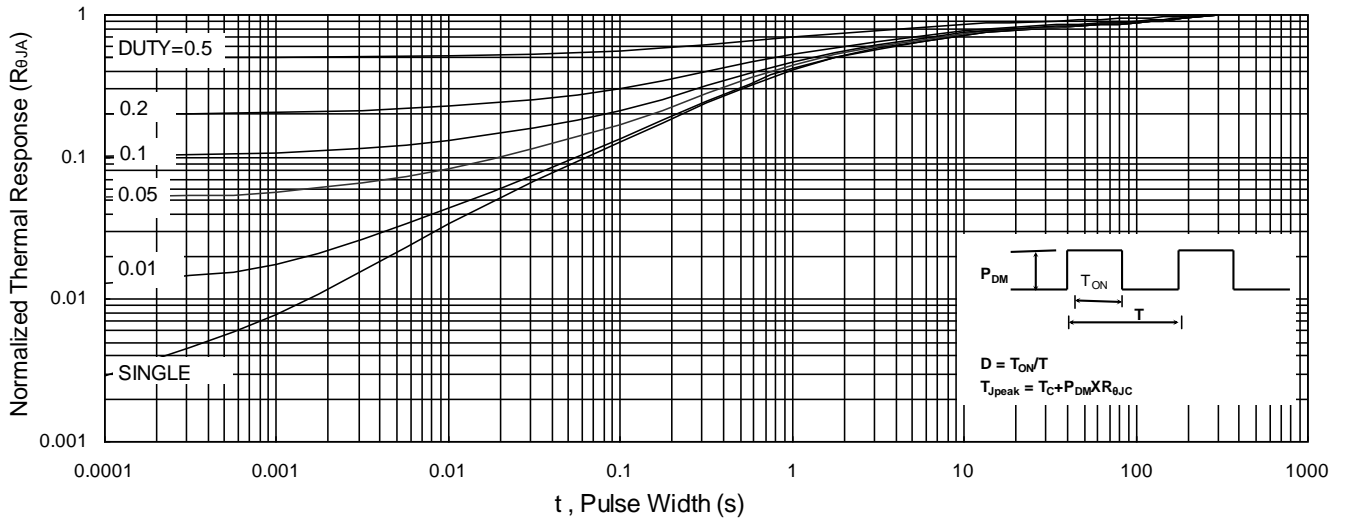


Fig.9 Normalized Maximum Transient Thermal Impedance

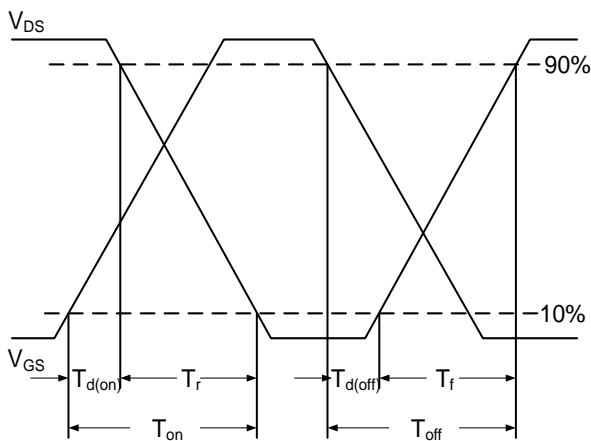


Fig.10 Switching Time Waveform

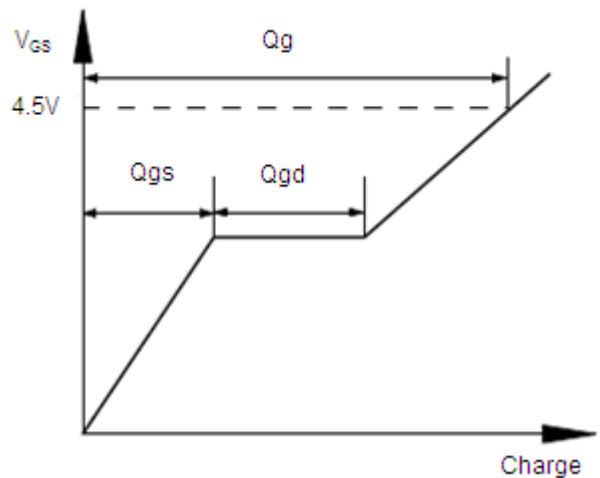
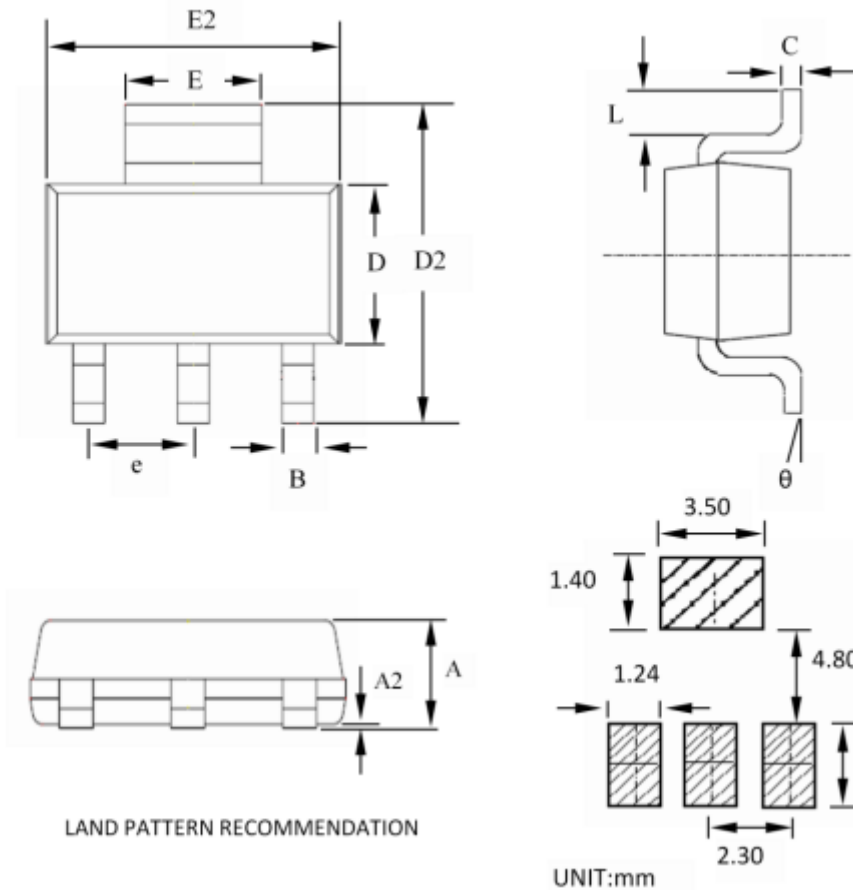


Fig.11 Gate Charge Waveform

SOT-223 Package Outline Dimensions



| SYMBOLS | MILLIMETERS | | | INCHES | | |
|---------|-------------|------|------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 1.50 | -- | 1.80 | 0.059 | -- | 0.071 |
| A2 | 0.02 | -- | 0.10 | 0.001 | -- | 0.004 |
| B | 0.60 | 0.70 | 0.84 | 0.024 | 0.028 | 0.033 |
| C | 0.23 | -- | 0.35 | 0.009 | -- | 0.014 |
| D | 3.30 | 3.50 | 3.70 | 0.130 | 0.138 | 0.146 |
| D2 | 6.70 | -- | 7.30 | 0.264 | -- | 0.287 |
| E | 2.90 | 3.00 | 3.10 | 0.114 | 0.118 | 0.122 |
| E2 | 6.30 | 6.50 | 6.70 | 0.248 | 0.256 | 0.264 |
| L | 0.75 | 0.90 | 1.00 | 0.030 | 0.035 | 0.039 |
| θ | 0° | -- | 10° | 0° | -- | 10° |
| e | -- | 2.30 | -- | -- | 0.091 | -- |

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